

6. 9. A method for chemically and mechanically planarizing a workpiece surface comprising the following steps:

providing a non-cellular lapping surface; and

effecting relative movement between said lapping surface and said workpiece surface in the presence of an abrasive slurry to planarize said workpiece surface.

7. 10. A method as claimed in claim 9, and further comprising the step of making said lapping surface from a soft and pliable material that will conform to integrated circuit device layers formed on said workpiece surface and resist damage to said integrated circuit device layers.

REMARKS


Entry of this amendment is respectfully requested prior to substantive examination of this application.

An Information Disclosure Statement and copies of references listed therein are also submitted with this Amendment. Please note that additional copies of the references already submitted or cited in parent application serial no. 08/662,678 are not included.

By this amendment, claims 1-3, which were the originally-filed claims in the parent of this continuation application, are canceled. New claims 4-10 are added. It is submitted that as new claims 4-10 distinguish over the prior art of record, allowance of this application is proper.

Respectfully submitted,

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